## General Description

The MAX17108 includes a 10-channel high-voltage level-shifting scan driver and a VCOM amplifier. The device is optimized for thin-film transistor (TFT) liquidcrystal display (LCD) applications.

The high-voltage level-shifting scan driver can swing from +38 V to -12 V and can swiftly drive capacitive loads. There are two positive supply inputs, which provide flexibility for system design.
The operational amplifier features rail-to-rail output, high short-circuit output current, fast slew rate, and wide bandwidth.

The MAX17108 is available in a 28 -pin, $5 \mathrm{~mm} \times 5 \mathrm{~mm}$, lead-free thin QFN package with a maximum thickness of 0.8 mm for thin LCD panels.

Applications
LCD TVs
LCD Monitors

| Features |
| :--- |
| High-Current, High-Speed Operational Amplifier |
| $\pm 200 \mathrm{~mA}$ Output Short-Circuit Current |
| $100 \mathrm{~V} / \mu \mathrm{s}$ Slew Rate |
| 20 MHz to 3dB Bandwidth |
| Rail-to-Rail Outputs |
| High-Voltage Level-Shifting Scan Drivers |
| Logic-Level Inputs |
| $\quad+38 \mathrm{~V}$ to -12V Outputs |
| Thermal-Overload Protection |
| 28-Pin, $5 \mathrm{~mm} \times 5 \mathrm{~mm}$ Thin QFN Package |

Ordering Information

| PART | TEMP RANGE | PIN-PACKAGE |
| :---: | :---: | :---: |
| MAX $17108 \mathrm{ETI}+$ | $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ | 28 Thin QFN-EP ${ }^{*}$ |

+Denotes a lead-free/RoHS-compliant package. *EP = Exposed pad.


Pin Configuration

TOP VIEW


THIN QFN
$5 \mathrm{~mm} \times 5 \mathrm{~mm}$
*EP = EXPOSED PAD

## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## ABSOLUTE MAXIMUM RATINGS

| A1-A10 to GN | -0.3V to +7.5V |
| :---: | :---: |
| AVDD to GND | -0.3V to +22V |
| POS, NEG, VCOM to GND | -0.3V to (VAVDD to +0.3 V ) |
| POS to NEG | ...........-6V to +6V |
| GON1, GON2 to GND | .-0.3V to +40V |
| GOFF to GND | -14V to +0.3V |
| Y1-Y6, Y9, Y10 to GND. | (VGOFF - 0.3V) to (VGON1 + 0.3V) |
| Y7, Y8 to GND | (VGOFF - 0.3V) to (VGON2 + 0.3V) |
| Y1-Y10 Load RMS Current | ...................... 140 mA |


| GON1, GON2 RMS Current | 350mA |
| :---: | :---: |
| GOFF RMS Current | 450 mA |
| Continuous Power Dissipation ( $\mathrm{T}_{\mathrm{A}}=+70^{\circ} \mathrm{C}$ ) |  |
| $28-P i n, 5 \mathrm{~mm} \times 5 \mathrm{~mm}$ Thin QF |  |
| (derate $34.5 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ ) | 2758.6 mW |
| Junction Temperature | $+150^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| Lead Temperature (soldering, 10s) | $+300^{\circ}$ |

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS

(Figure 1 circuit, $V_{A V D D}=16 \mathrm{~V}, \mathrm{~V}_{G O N}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathbf{T}_{\mathbf{A}}=\mathbf{0}^{\circ} \mathbf{C}$ to $+85^{\circ} \mathbf{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)

| PARAMETER | CONDITIONS | MIN | TYP | MAX |
| :--- | :--- | :--- | :---: | :---: | UNITS

## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## ELECTRICAL CHARACTERISTICS (continued)

(Figure 1 circuit, $\mathrm{V}_{\mathrm{AVDD}}=16 \mathrm{~V}, \mathrm{~V}_{\mathrm{GON}}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathbf{T}_{\mathbf{A}}=\mathbf{0}^{\circ} \mathbf{C}$ to $+85^{\circ} \mathbf{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)

| PARAMETER | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
| OPERATIONAL AMPLIFIER |  |  |  |  |  |
| AVDD Supply Range |  | 6 |  | 20 | V |
| AVDD Supply Current | Buffer configuration, $\mathrm{V}_{\text {POS }}=\mathrm{V}_{\text {AVDD }} / 2$, no load |  |  | 6 | mA |
| Input Offset Voltage | $2 \mathrm{~V}<\left(\mathrm{V}_{\text {NEG }}, \mathrm{V}_{\text {POS }}\right)<\left(\mathrm{V}_{\text {AVDD }}-2 \mathrm{~V}\right), \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | -10 |  | +10 | mV |
| Input Bias Current | $\mathrm{V}_{\text {NEG, }}, \mathrm{V}_{\text {POS }}=\mathrm{V}_{\text {AVDD }} / 2, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | -50 |  | +50 | nA |
| Input Common-Mode Voltage Range |  | 0 |  | $V_{\text {AVDD }}$ | V |
| Input Common-Mode Rejection Ratio | $2 \mathrm{~V}<\left(\mathrm{V}_{\text {NEG }}, \mathrm{V}_{\text {POS }}\right)<\left(\mathrm{V}_{\text {AVDD }}-2 \mathrm{~V}\right)$ |  | 80 |  | dB |
| Output-Voltage Swing High | $\operatorname{IVCOM}=50 \mathrm{~mA}$ | $\begin{gathered} \text { VAVDD - } \\ 400 \end{gathered}$ |  |  | mV |
| Output-Voltage Swing Low | IVCOM $=-50 \mathrm{~mA}$ |  |  | 400 | mV |
| Large-Signal Voltage Gain | $\mathrm{V}_{\mathrm{VCOM}}=1 \mathrm{~V}$ to $\mathrm{V}_{\text {AVDD }}-1 \mathrm{~V}$ |  | 80 |  | dB |
| Slew Rate |  |  | 100 |  | V//us |
| -3dB Bandwidth |  |  | 20 |  | MHz |
| Short-Circuit Current | Short to $\mathrm{V}_{\text {AVDD }} / 2$, sourcing |  | 230 |  | mA |
|  | Short to $\mathrm{V}_{\text {AVDD }} / 2$, sinking |  | 460 |  |  |
| FAULT DETECTION |  |  |  |  |  |
| Thermal Shutdown | Rising edge, typical hysteresis $=10^{\circ} \mathrm{C}$, not latched |  | +155 |  | ${ }^{\circ} \mathrm{C}$ |
| CONTROL INPUTS |  |  |  |  |  |
| Logic-Input Voltage Range (A1-A10) | (Note 3) |  |  | 6 | V |
| Logic-Input Voltage Low (A1-A10) |  |  |  | 0.8 | V |
| Logic-Input Voltage High (A1-A10) |  | 2 |  |  | V |
| Logic-Input Bias Current (A1-A10) | $0<\mathrm{V}_{\mathrm{A}}<6 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$ | -1 |  | +1 | $\mu \mathrm{A}$ |

## ELECTRICAL CHARACTERISTICS

(Figure 1 circuit, $\mathrm{V}_{\text {AVDD }}=16 \mathrm{~V}, \mathrm{~V}_{G O N}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathbf{T}_{\mathbf{A}}=-\mathbf{4 0 ^ { \circ }} \mathbf{C}$ to $+85^{\circ} \mathbf{C}$, unless otherwise noted.) (Note 2)

| PARAMETER | CONDITIONS | MIN | TYP MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: |
| HIGH-VOLTAGE DRIVER BLOCK |  |  |  |  |
| GON_ Input Voltage Range |  | 12 | 38 | V |
| GOFF Input Voltage Range |  | -12 | -4 | V |
| GOFF Supply Current | A1-A10 = GND, no load |  | 300 | $\mu \mathrm{A}$ |
| GON_ Total Supply Current | A1-A10 = GND, no load |  | 540 | $\mu \mathrm{A}$ |
| Output-Voltage Low (Y1-Y10) | $I Y_{-}=10 \mathrm{~mA}$ |  | $\begin{aligned} & \text { VGOFF } \\ & +0.06 \end{aligned}$ | V |
| Output-Voltage High (Y1-Y10) | $\mathrm{I}_{\mathrm{Z}}=10 \mathrm{~mA}$ | $\begin{gathered} \text { VGON- } \\ -0.25 \end{gathered}$ |  | V |

## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## ELECTRICAL CHARACTERISTICS (continued)

(Figure 1 circuit, $\mathrm{V}_{\text {AVDD }}=16 \mathrm{~V}, \mathrm{~V}_{G O N}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathbf{T}_{\mathbf{A}}=\mathbf{- 4 0 ^ { \circ }} \mathbf{C}$ to $\mathbf{+ 8 5}{ }^{\circ} \mathbf{C}$, unless otherwise noted.) (Note 2)

| PARAMETER | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: |
| OPERATIONAL AMPLIFIER |  |  |  |  |  |
| AVDD Supply Range |  | 6 |  | 20 | V |
| AVDD Supply Current | Buffer configuration, $\mathrm{V}_{\text {POS }}=\mathrm{V}_{\text {AVDD }} / 2$, no load |  |  | 6 | mA |
| Input Common-Mode Voltage Range |  | 0 |  | $V_{\text {AVDD }}$ | V |
| Output-Voltage Swing High | $\mathrm{I} \mathrm{VCOM}=50 \mathrm{~mA}$ | $\begin{gathered} \text { VAVDD - } \\ 400 \end{gathered}$ |  |  | mV |
| Output-Voltage Swing Low | Ivcom $=-50 \mathrm{~mA}$ |  |  | 400 | mV |
| CONTROL INPUTS |  |  |  |  |  |
| Logic-Input Voltage Range (A1-A10) | (Note 3) |  |  | 6 | V |
| Logic-Input Voltage Low (A1-A10) |  |  |  | 0.8 | V |
| Logic-Input Voltage High (A1-A10) |  | 2 |  |  | V |

Note 1: The load models for different channels are illustrated in Figure 2.
Note 2: $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ specifications are guaranteed by design, not production tested.
Note 3: For $5.5 \mathrm{~V}<\mathrm{V}_{\mathrm{A}_{-}}<6 \mathrm{~V}$, use the IC for no longer than $1 \%$ of IC lifetime. For continuous operation, voltage should not exceed 5.5 V .

## Typical Operating Characteristics

(Circuit of Figure 1, $\mathrm{V}_{\text {AVDD }}=16 \mathrm{~V}, \mathrm{VGON}_{\mathrm{G}}=38 \mathrm{~V}, \mathrm{VGOFF}=-12 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


# 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels 

Typical Operating Characteristics (continued)
(Circuit of Figure 1, $\mathrm{V}_{\mathrm{AVDD}}=16 \mathrm{~V}, \mathrm{~V}_{G O N_{-}}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)


200ns/div

SCAN DRIVER OUTPUT RISING EDGE (Y9 AND Y10) PROPAGATION DELAY AND RISE TIME


10ns/div


SCAN DRIVER OUTPUT FALLING EDGE (Y7 AND Y8) PROPAGATION DELAY AND FALL TIME


200ns/div

SCAN DRIVER OUTPUT FALLING EDGE (Y9 AND Y10)


10ns/div

OPERATIONAL AMPLIFIER POWER-SUPPLY REJECTION RATIO


## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## Typical Operating Characteristics (continued)

(Circuit of Figure 1, $\mathrm{V}_{\text {AVDD }}=16 \mathrm{~V}, \mathrm{VGON}_{-}=38 \mathrm{~V}, \mathrm{VGOFF}^{\prime}=-12 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)

OPERATIONAL AMPLIFIER RAIL-TO-RAIL INPUT/OUTPUT WAVEFORMS


10us/div

OPERATIONAL AMPLIFIER LARGE-SIGNAL STEP RESPONSE


AVDD SUPPLY QUIESCENT CURRENT vs. AVDD SUPPLY VOLTAGE


OPERATIONAL AMPLIFIER LOAD-TRANSIENT RESPONS


20us/div

OPERATIONAL AMPLIFIER SMALL-SIGNAL STEP RESPONSE


GON1 SUPPLY QUIESCENT CURRENT vs. GON1 SUPPLY VOLTAGE


# 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels 

## Typical Operating Characteristics (continued)

(Circuit of Figure 1, $\mathrm{V}_{\mathrm{AVDD}}=16 \mathrm{~V}, \mathrm{~V}_{\mathrm{GON}}=38 \mathrm{~V}, \mathrm{~V}_{\mathrm{GOFF}}=-12 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=0^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$. Typical values are at $\mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}$, unless otherwise noted.)



Pin Description

| PIN | NAME | FUNCTION |
| :---: | :---: | :--- |
| $1-9$ | A9-A1 | Level-Shifter Logic-Level Input |
| 10 | GON1 | Gate-On Supply Input 1. GON1 is the positive supply for the Y1-Y6, Y9, and Y10 level shifters. <br> Bypass GON1 with a minimum of $1 \mu$ F ceramic capacitor to GND. |
| 11 | GOFF | Gate-Off Supply Input. GOFF is the negative supply for the Y1-Y10 level shifters. Bypass GOFF with <br> a minimum of 1 $\mu \mathrm{F}$ ceramic capacitor to GND. |
| 12 | GON2 | Gate-On Supply Input 2. GON2 is the positive supply for the Y7 and Y8 level shifters. Bypass GON2 <br> with a minimum of 1 $\mu \mathrm{F}$ ceramic capacitor to GND. |
| $13-22$ | Y1-Y10 | Level-Shifter Outputs |
| 23 | GND | Ground |
| 24 | AVDD | Operational Amplifier Supply Voltage. Bypass AVDD with a minimum of 1uF ceramic capacitor to GND. |
| 25 | VCOM | Operational Amplifier Output |
| 26 | NEG | Operational Amplifier Negative Input |
| 27 | POS | Operational Amplifier Positive Input |
| 28 | A10 | Level-Shifter Logic-Level Input |
| - | EP | Exposed Backside Pad. Connect to VGOFF. Copper area should be maximized for thermal <br> performance. |

## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## Detailed Description

The MAX17108 includes a 10-channel, high-voltage levelshifting scan driver, an operational amplifier for VCOM, and a linear regulator that provides the internal bias for the step-up controller. Figure 1 shows the MAX17108 functional block diagram and typical operating circuit.


Figure 1. Functional Block Diagram and Typical Operating Circuit

## Load Models for Different Channels

Figure 2 shows the load models for different channels.


Figure 2. Load Models for Different Channels

## Operational Amplifier

The MAX17108 has one operational amplifier that is typically used to drive the LCD backplane (VCOM). The operational amplifier features a $\pm 200 \mathrm{~mA}$ output shortcircuit current, $100 \mathrm{~V} / \mu \mathrm{s}$ slew rate, 20 MHz bandwidth, and rail-to-rail output.

## Short-Circuit Current Limit

The operational amplifier limits the short-circuit current to approximately $\pm 200 \mathrm{~mA}$. If the short-circuit condition persists, the junction temperature of the IC rises until it reaches the thermal-shutdown threshold $\left(+155^{\circ} \mathrm{C}\right.$ typ $)$. Once the junction temperature reaches the thermalshutdown threshold, an internal thermal sensor shuts off the operational amplifier. The thermal protection is not latched and the device recovers once the temperature drops below the hysteretic threshold ( $+10^{\circ} \mathrm{C}$ typ).

# 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels 


#### Abstract

Driving Pure Capacitive Loads The operational amplifier is typically used to drive the LCD backplane (VCOM). The LCD backplane consists of a distributed series capacitance and resistance, a load that can be easily driven by the operational amplifier. However, if the operational amplifier is used in an application with a pure capacitive load, steps must be taken to ensure stable operation. As the operational amplifier's capacitive load increases, the amplifier's bandwidth decreases and gain peaking increases. A $5 \Omega$ to $50 \Omega$ resistor placed between VCOM and the capacitive load reduces peaking but also reduces the gain. An alternative method of reducing peaking is to place a series RC network (snubber) in parallel with the capacitive load. The RC network does not continuously load the output or reduce the gain. Typical values of the resistor are between $100 \Omega$ and $200 \Omega$ and the typical value of the capacitor is 10 pF .


High-Voltage Level-Shifting Scan Driver The MAX17108 includes 10 logic-level to high-voltage level-shifting buffers, which can buffer 10 logic inputs (A1-A10) and shift them to a desired level (Y1-Y10) to drive TFT-LCD row logic. The driver outputs, Y1-Y10, swing between their power-supply rails, according to the input-logic level on A1-A10. The driver output is VGOFF when its respective input is logic-low, and VGON_ when its respective input is logic-high.
These 10 driver channels are grouped for different high-level supplies. A1-A6 and A9-A10 are supplied from GON1; A7 and A8 are supplied from GON2.
The high-voltage, level-shifting scan drivers swing from +38 V to -12 V and can swiftly drive capacitive loads. The typical propagation delays are 35ns.

## Thermal Shutdown

The MAX17108 includes a thermal-protection circuit. When the local IC temperature exceeds $+155^{\circ} \mathrm{C}$ (typ), the device shuts down and recovers when the die temperature drops by $10^{\circ} \mathrm{C}$ (typ).

## Design Procedure

All MAX17108 designs should be prototyped and tested prior to production. Table 1 provides a list of components for the typical operating circuit. Table 2 shows a component supplier.

Table 1. Component List

| DESIGNATION | DESCRIPTION |
| :--- | :--- |
| $1 \mu \mathrm{~F}$ bypassing <br> capacitors | $1 \mu \mathrm{~F} \pm 10 \%, 50 \mathrm{~V}$ X7R ceramic capacitors <br> $(0805)$ <br> Murata GRM21BR71H105K |
| $0.1 \mu \mathrm{~F}$ bypassing <br> capacitors | $0.1 \mu \mathrm{~F} \pm 10 \%, 25 \mathrm{~V}$ X5R ceramic capacitors <br> $(0603)$ <br> Murata GRM188R61E104K |

Table 2. Component Supplier

| SUPPLIER | PHONE | WEBSITE |
| :---: | :---: | :---: |
| Murata Electronic North <br> America, Inc. | $770-436-1300$ | www.murata.com |

## Applications Information

## Power Dissipation

An IC's maximum power dissipation depends on the thermal resistance from the die to the ambient environment and the ambient temperature. The thermal resistance depends on the IC package, PCB copper area, other thermal mass, and airflow.
The MAX17108, with its exposed backside pad soldered to $1 \mathrm{in}^{2}$ of PCB copper, can dissipate approximately 2700 mW into $+70^{\circ} \mathrm{C}$ still air. More PCB copper, cooler ambient air, and more airflow increase the possible dissipation, while less copper or warmer air decreases the IC's dissipation capability. The major components of power dissipation are the power dissipated in the operational amplifier and the high-voltage scan drivers.

## Operational Amplifier

The power dissipated in the operational amplifiers depends on the output current, the output voltage, and the supply voltage:

$$
\begin{gathered}
\text { PD } \text { SOURCE }=I_{\text {VCOM_SOURCE }} \times\left(\mathrm{V}_{\text {AVDD }}-\mathrm{V}_{\text {VCOM }}\right) \\
\mathrm{PD}_{\text {SINK }}=I_{\text {VCOM_SINK }} \times \mathrm{V}_{\mathrm{VCOM}}
\end{gathered}
$$

where IVCOM_SOURCE is the output current sourced by one operational amplifier, and IVCOM_SINK is the output current that the operational amplifier sinks.
In a typical case, where the supply voltage is 8 V and the output voltage is 4 V with an output source current of 30 mA for the operational amplifier, the power dissipated is 120 mW .

## 10-Channel High-Voltage Scan Driver and VCOM Amplifier for TFT LCD Panels

## Scan Driver Outputs

When driving a pure capacitive load, the power dissipated by the scan driver outputs (A1-A6; A7-A10 are low-frequency outputs and the power dissipation by these outputs can be omitted) depends on the scan frequency, the capacitive load, and the difference between the GON1 and GOFF supply voltages:

$$
\mathrm{PD}_{\mathrm{SCAN}}=6 \times \mathrm{f}_{\mathrm{SCAN}} \times \mathrm{C}_{\text {PANEL }} \times\left(\mathrm{V}_{\mathrm{GON} 1}-\mathrm{V}_{\mathrm{GOFF}}\right)^{2}
$$

If the six scan drivers operate at a frequency of 50 kHz , the load of the six outputs is 5 nF , and the supply voltage difference is 30 V , then the power dissipated is 1.35 W .

## PCB Layout Guidelines

Careful PCB layout is important for proper operation. Use the following guidelines for good PCB layout:

- Avoid using vias in the high-current paths. If vias are unavoidable, use many vias in parallel to reduce resistance and inductance.
- Create VGoff plane, connect it to EP.
- Create a ground island (GND) consisting of the input and output capacitor grounds and GND pin. Connect all these together with short, wide traces or a small ground plane.
- Place the voltage-divider resistors as close as possible to the POS pin. The divider's center trace should be kept short. Placing the resistors far away causes the POS trace to become an antenna that can pick up switching noise.
- Minimize the length and maximize the width of the traces between the output capacitors and the load for best transient responses.
Refer to the MAX17108 Evaluation Kit for an example of proper board layout.


## Chip Information

TRANSISTOR COUNT: 2918
PROCESS: BiCMOS

Package Information
For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

| PACKAGE TYPE | PACKAGE CODE | DOCUMENT NO. |
| :---: | :---: | :---: |
| 28 TQFN | T2855-6 | $\underline{\mathbf{2 1 - 0 1 4 0}}$ |

